# **Power MOSFET Dual P-Channel ChipFET™**

## 3.0 Amps, 8 Volts

#### **Features**

- Low R<sub>DS(on)</sub> for Higher Efficiency
- Logic Level Gate Drive
- Miniature ChipFET Surface Mount Package

#### **Applications**

 Power Management in Portable and Battery-Powered Products; i.e., Cellular and Cordless Telephones and PCMCIA Cards

#### **MAXIMUM RATINGS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	5 secs	Steady State	Unit
Drain-Source Voltage	V <sub>DS</sub>	-8	3.0	V
Gate-Source Voltage	V <sub>GS</sub>	±	3.0	V
Continuous Drain Current $(T_J = 150^{\circ}C)$ (Note 1) $T_A = 25^{\circ}C$ $T_A = 85^{\circ}C$	ID	±4.1 ±2.9	±3.0 ±2.2	A
Pulsed Drain Current	I <sub>DM</sub>	±	10	Α
Continuous Source Current (Diode Conduction) (Note 1)	Is	-1.8	-0.9	Q
Maximum Power Dissipation (Note 1)  T <sub>A</sub> = 25°C  T <sub>A</sub> = 85°C	P <sub>D</sub>	2.1 1.1	1.1 0.6	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to	+150	°C

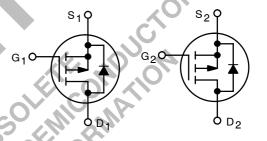
1. Surface Mounted on 1" x 1" FR4 Board.



#### ON Semiconductor®

http://onsemi.com

DUAL P-CHANNEL 3.0 AMPS, 8 VOLTS  $R_{DS(on)} = 90 \text{ m}\Omega$ 



P-Channel MOSFET

P-Channel MOSFET



ChipFET CASE 1206A STYLE 2

# PIN CONNECTIONS MARKING DIAGRAM D1 8 1 S1 1 O 8 7 D2 6 3 S2 3 6 6 D2 5 4 G2 4 6 5

A9 = Specific Device Code

#### **ORDERING INFORMATION**

Device	Package	Shipping
NTHD5905T1	ChipFET	3000/Tape & Reel

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Тур	Max	Unit
Maximum Junction-to-Ambient (Note 2) t ≤ 5 sec Steady State	R <sub>thJA</sub>	50 90	60 110	°C/W
Maximum Junction-to-Foot (Drain) Steady State	$R_{thJF}$	30	40	°C/W

### **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Test Condition	Min	Тур	Max	Unit
Static			•			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-0.45	_	-	V
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8.0 \text{ V}$	-	-	±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -6.4 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	-1.0	μΑ
		$V_{DS} = -6.4 \text{ V}, V_{GS} = 0 \text{ V},$ $T_{J} = 85^{\circ}\text{C}$	-	_	-5.0	
On-State Drain Current (Note 3)	I <sub>D(on)</sub>	$V_{DS} \le -5.0 \text{ V}, V_{GS} = -4.5 \text{ V}$	-10	-,(	<b>)</b> -	Α
Drain-Source On-State Resistance (Note 3)	r <sub>DS(on)</sub>	$V_{GS} = -4.5 \text{ V}, I_D = -3.0 \text{ A}$	-	0.075	0.090	Ω
		$V_{GS} = -2.5 \text{ V}, I_D = -2.5 \text{ A}$	-	0.110	0.130	
		$V_{GS} = -1.8 \text{ V}, I_D = -1.0 \text{ A}$	-1	0.150	0.180	
Forward Transconductance (Note 3)	9 <sub>fs</sub>	$V_{DS} = -5.0 \text{ V}, I_{D} = -3.0 \text{ A}$	(O)	7.0	-	S
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	$I_S = -0.9 \text{ A}, V_{GS} = 0 \text{ V}$	7 - 4	-0.8	-1.2	V
Dynamic (Note 4)		02 (1)	011	•		
Total Gate Charge	$Q_g$	0, 8,	) -	5.5	9.0	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -4.0 \text{ V}, V_{GS} = -4.5 \text{ V},$ $I_{D} = -3.0 \text{ A}$	_	0.5	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	1.5	-	
Turn-On Delay Time	t <sub>d(on)</sub>	(0,11,0)	-	10	15	ns
Rise Time	t <sub>r</sub>	$V_{DD} = -4.0 \text{ V, R}_{L} = 4 \Omega$ $I_{D} \cong -1.0 \text{ A, V}_{GEN} = -4.5 \text{ V,}$	_	45	70	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong -1.0 \text{ A}, V_{GEN} = -4.5 \text{ V},$ $R_G = 6 \Omega$	_	30	45	
Fall Time	St <sub>f</sub>		_	10	15	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = -0.9 A, di/dt = 100 A/μs	-	30	60	1

Surface Mounted on 1" x 1" FR4 Board.
 Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Guaranteed by design, not subject to production testing.

#### TYPICAL ELECTRICAL CHARACTERISTICS

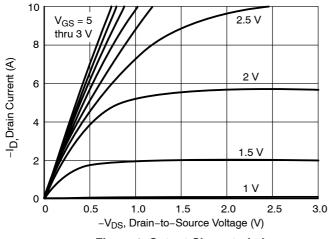


Figure 1. Output Characteristics

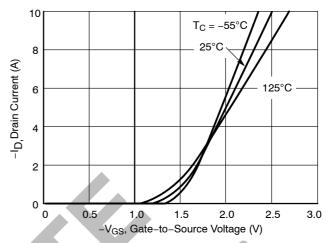


Figure 2. Transfer Characteristics

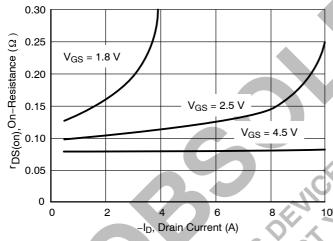


Figure 3. On-Resistance vs. Drain Current

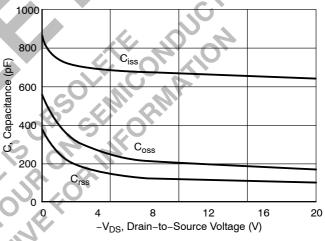


Figure 4. Capacitance

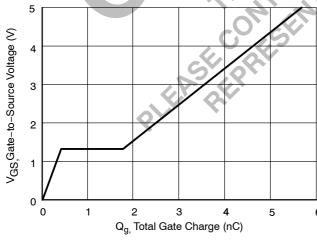


Figure 5. Gate Charge

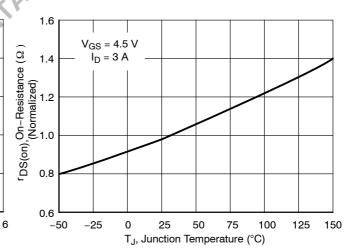


Figure 6. On–Resistance vs. Junction Temperature

#### TYPICAL ELECTRICAL CHARACTERISTICS

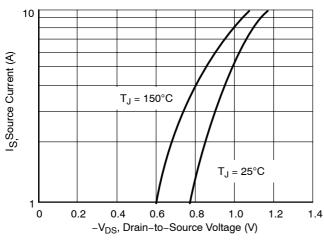


Figure 7. Source Diode Forward Voltage

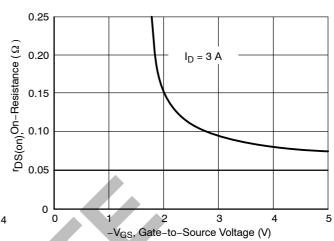
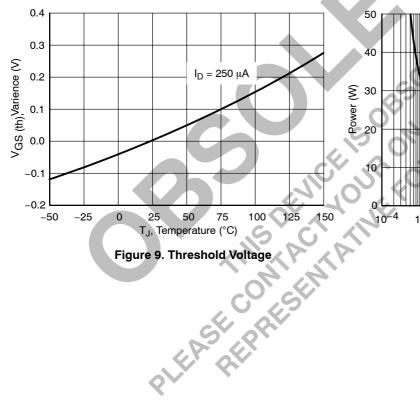


Figure 8. On-Resistance vs. Gate-to-Source Voltage



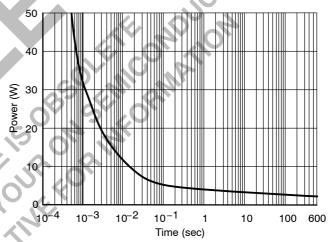


Figure 10. Single Pulse Power

#### TYPICAL ELECTRICAL CHARACTERISTICS

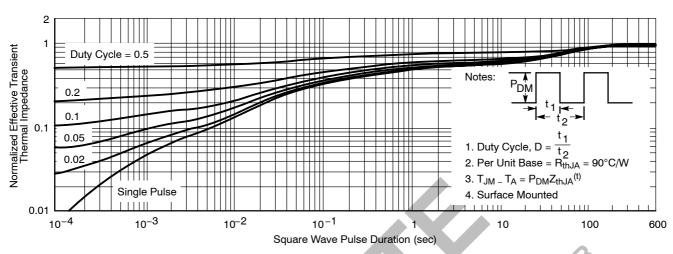
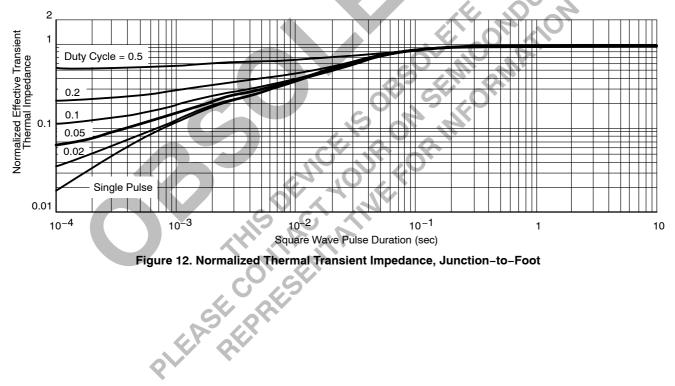


Figure 11. Normalized Thermal Transient Impedance, Junction-to-Ambient

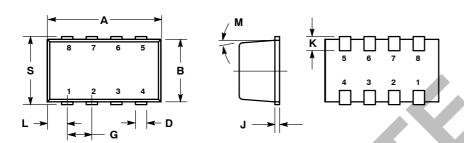


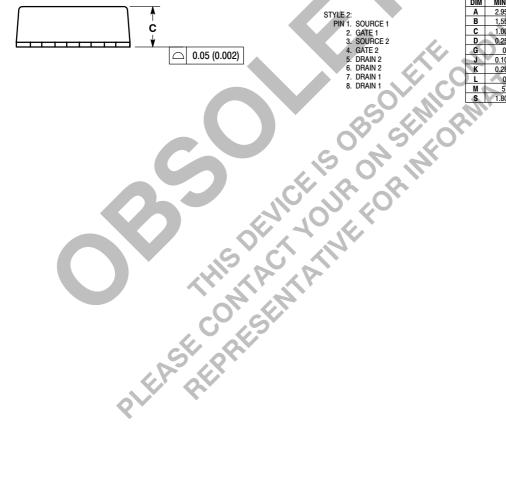
# **Notes**



#### PACKAGE DIMENSIONS

#### **ChipFET** CASE 1206A-03 ISSUE D





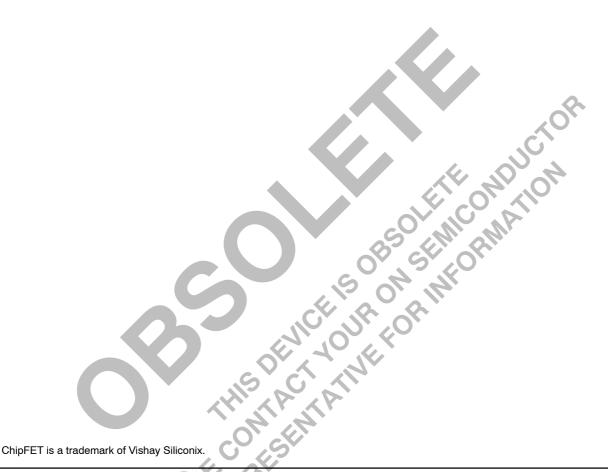
STYLE 2: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2

#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
  3. MOLD GATE BURRS SHALL NOT EXCEED 0.13 MM
- PER SIDE.

  4. LEADFRAME TO MOLDED BODY OFFSET IN
  HORIZONTAL AND VERTICAL SHALL NOT EXCEED 0.08 MM
- DIMENSIONS A AND B EXCLUSIVE OF MOLD GATE RURRS
- NO MOLD FLASH ALLOWED ON THE TOP AND
- BOTTOM LEAD SURFACE. 1206A-01 AND 1206A-02 OBSOLETE. NEW STANDARD IS 1206A-03.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	2.95	3.10	0.116	0.122	
В	1.55	1.70	0.061	0.067	
С	1.00	1.10	0.039	0.043	
D	0.25	0.35	0.010	0.014	
G	0.65 BSC		0.025 BSC		
J	0.10	0.20	0.004	0.008	
K	0.28	0.42	0.011	0.017	
Ĺ	0.55 BSC		0.022 BSC		
M (	5° NOM		5 ° NOM		
S	1.80	2.00	0.072	0.080	



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